SEMI AUTOMATIC DIE BONDER

T-3202

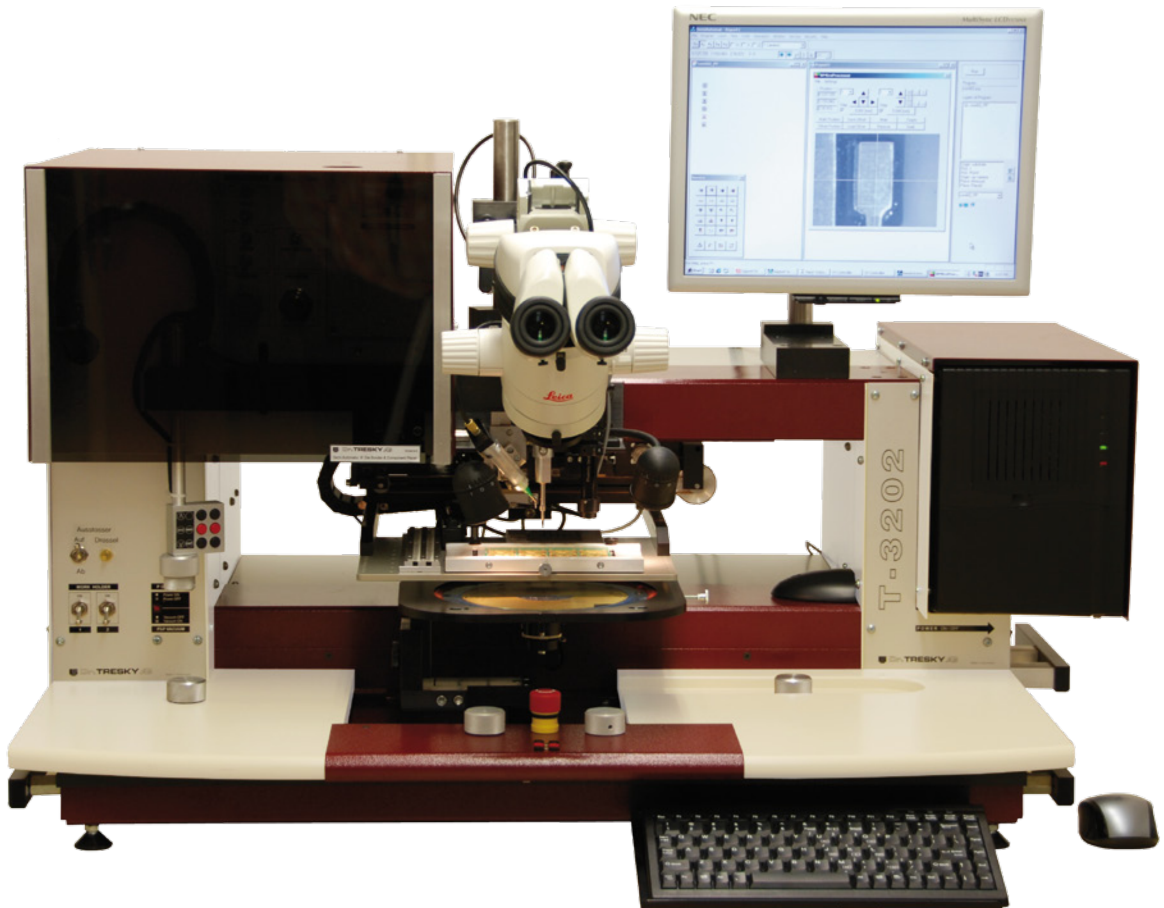
MICRO ASSEMBLY

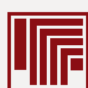
T-3202

The T-3202 represents a new generation of Windows operated, electronic assembly equipment, featuring a highest possible flexibility and enabling a cost effective solution of a broad variety of applications. As with all of Tresky's products, this semi automatic die bonder , incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height.

The T-3202 is equiped with Tresky's die ejector system for pick-up from wafer.

- True Vertical Technology™
- Unique pick-up from wafer
- 4 Axis programmable
- Multi functional software





TRESKY

Dr. TRESKY AG Switzerland Email: tresky@tresky.com www.tresky.com

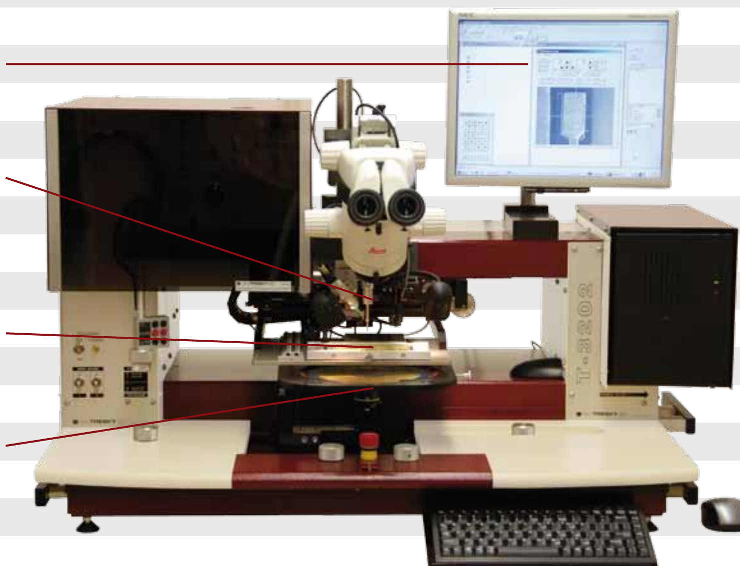
A highly universal die attach system **T-3202**, designed for both development and lower or middle productions runs. Flexible Windows based software provide easy teach-in programming, quick switch-over to another process and re-producible product quality. Modular structure and number of optional equipment enable optimal configuration for the user's requirement.

APPLICATIONS:

Die Attach, Die Sorting, Flip-Chip, 3D Packaging / Stacking, MEMS, MOEMS, VCSEL, Photonics, Ultrasonic, Thermo-sonic, RFID, Sensor Assembly, Adhesive Bonding, Eutectic Bonding (AuAu, AuSn, ...), ...

FEATURES AND OPTIONS:

- Interface for all neccesary XYZ and T parameters, temperature profile, video imaging of up and down looking camera, Inspection or Flip-Chip.
- TRUE VERTICAL TECHNOLOGY™, Z-movement 95mm with motorized 360° Tool rotation; Dispenser, Stamping, Ultrasonic, Scrub,Tool Heating, Pre Form Spindle, ...
- Motorized XY placement stage supporting: Waffle/Gel - Pack -, Substrate - Holder, various Heating Plates or other Fixtures
- Pick-up from Wafer with Tresky's patented die ejector system, especialy suitable for all kind of Si, GaAs and InP dies down to 30μm thickness.



TECHNICAL DATA:

XY- Movement (placement stage):	220mm x 220mm (automatic)
XY- Movement (wafer stage):	220mm x 220mm (manual)
Z- Movement:	95mm (automatic)
Spindle Rotation:	360° (manual / optional: automatic)
Bond Force (standard range):	40g - 400g (other force ranges available)
Bond Force (repeatability):	±1g
Z-Measurement resolution:	±0.001mm
Max. PC Board-/ Substrate Size:	400mm x 280mm
Placement accuracy:	±5μm
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	900mm x 800mm x 700mm
Weight:	11kg
Voltage:	110V / 220V

Note: All specifications are subject to change without notice

REPRESENTED BY:

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